CPC COOPERATIVE PATENT CLASSIFICATION

H ELECTRICITY

(NOTE omitted)

H01 ELECTRIC ELEMENTS

(NOTES omitted)

H01F MAGNETS; INDUCTANCES; TRANSFORMERS; SELECTION OF MATERIALS FOR

THEIR MAGNETIC PROPERTIES (ceramics based on ferrites <u>C04B 35/26</u>; alloys <u>C22C</u> {; construction of loading coils <u>H01B</u>}; loudspeakers, microphones, gramophone pick-ups or like acoustic electromechanical transducers <u>H04R</u>; thermomagnetic devices <u>H10N 15/00</u>)

NOTE

In this subclass, inductances and transformers are regarded as being "for power supply" if they are intended for this purpose even in systems operating at frequencies above 60 cycles/sec.

WARNING

In this subclass non-limiting references (in the sense of paragraph 39 of the Guide to the IPC) may still be displayed in the scheme.

1/00	Magnets or magnetic bodies characterised by the
	magnetic materials therefor; Selection of materials
	for their magnetic properties

NOTES

- Attention is drawn to Note (3) after the title of section C, which Note indicates to which version of the Periodic Table of chemical elements the CPC refers. In this group, the system used is the 8 group system indicated by Roman numerals in the Periodic Table thereunder.
- 2. {Group <u>H01F 1/0036</u> takes precedence over groups <u>H01F 1/09</u>, <u>H01F 1/11</u>, <u>H01F 1/20</u>, <u>H01F 1/33</u> and <u>H01F 1/36</u>.}
- 1/0009 {Antiferromagnetic materials, i.e. materials exhibiting a Néel transition temperature (H01F 1/0036 takes precedence)}
- 1/0018 {Diamagnetic or paramagnetic materials, i.e. materials with low susceptibility and no hysteresis (H01F 1/0036 takes precedence)}
- 1/0027 {Thick magnetic films (forming thick magnetic films $\underline{H01F}$ 41/16)}
- 1/0036 {showing low dimensional magnetism, i.e. spin rearrangements due to a restriction of dimensions, e.g. showing giant magnetoresistivity, (H01F 1/153, H01F 1/42 and H01F 10/00 take precedence; magnetoresistive sensors G01D 5/16, G01R 33/06; magnetoresistive recording G11B 5/39; magnetic-field-controlled resistors H10N 50/10)}
- 1/0045 • {Zero dimensional, e.g. nanoparticles, soft nanoparticles for medical/biological use (preparation of fullerenes in general C01B 32/15)}
- 1/0054 . . . {Coated nanoparticles, e.g. nanoparticles coated with organic surfactant}
- 1/0063 . . . {in a non-magnetic matrix, e.g. granular solids (granular films H01F 10/007)}
- 1/0072 • {one dimensional, i.e. linear or dendritic nanostructures}

1/0081		{in a non-magnetic matrix, e.g. Fe-nanowires
		in a nanoporous membrane}

- 1/009 . . {bidimensional, e.g. nanoscale period nanomagnet arrays (H01F 10/007 takes precedence)}
 1/01 . of inorganic materials (H01F 1/44 takes precedence)
- 1/012 • {adapted for magnetic entropy change by magnetocaloric effect, e.g. used as magnetic refrigerating material (refrigeration systems using magnetic effects F25B 21/00)}
- 1/015 . . . {Metals or alloys} 1/017 . . . {Compounds}
- 1/03 characterised by their coercivity $\{(\underline{\text{H01F 1/40}} \text{ takes precedence})\}$
- 1/0302 . . . {characterised by unspecified or heterogeneous hardness or specially adapted for magnetic hardness transitions}
- 1/0304 {adapted for large Barkhausen jumps or domain wall rotations, e.g. WIEGAND or MATTEUCCI effect (H01F 1/143 and H01F 1/15391 take precedence)}
- 1/0306 . . . {Metals or alloys, e.g. LAVES phase alloys of the MgCu₂-type (<u>H01F 1/0304</u> takes precedence)}
- 1/0308 { with magnetic shape memory [MSM], i.e. with lattice transformations driven by a magnetic field, e.g. Heusler alloys}
- 1/0311 {Compounds (<u>H01F 1/0304</u> takes precedence)}
- 1/0313 {Oxidic compounds}
- 1/0315 {Ferrites}
 1/0317 {Manganites}
 1/032 . . of hard-magnetic materials
- 1/04 . . . metals or alloys

1/047	Alloys characterised by their composition	1/09 mixtures of metallic and non-metallic
	NOTE	particles; metallic particles having oxide skin
		1/10 non-metallic substances, e.g. ferrites {, e.g.
	In groups $\underline{H01F 1/053} - \underline{H01F 1/059}$, an alloy is classified in the last appropriate	[(Ba,Sr)O(Fe ₂ O ₃) ₆] ferrites with hexagonal
	place	structure} 1/11 in the form of particles {(for magnetic
	•	1/11 in the form of particles {(for magnetic record carriers G11B 5/70626)}
1/053	containing rare earth metals	1/111 {with a non-magnetic core}
1/0533	· · · · · · {in a bonding agent}	1/112 { with a skin (<u>H01F 1/113</u> takes
1/0536	{sintered}	precedence)}
1/055	and magnetic transition metals, e.g.	1/113 in a bonding agent
1/0551	SmCo ₅ {in the form of particles, e.g.	1/117 Flexible bodies
1/0331	rapid quenched powders or ribbon	1/12 of soft-magnetic materials
	flakes}	1/14 metals or alloys
1/0552	• • • • • • { with a protective layer }	$1/143$ {in the form of wires ($\underline{\text{H01F } 1/147}$ takes
1/0553	{obtained by reduction or by	precedence)}
	hydrogen decrepitation or	1/147 Alloys characterised by their composition
	embrittlement}	{(treatment thereof for enhancing their electromagnetic properties <u>C21D 8/12</u>)}
1/0555	• • • • • {pressed, sintered or bonded	
1/0556	together}	NOTE
1/0556	{pressed}	In groups
1/0557 1/0558	{sintered} {bonded together}	<u>H01F 1/14708</u> - <u>H01F 1/15391</u> , an
1/0558		alloy is classified in the last appropriate
1/057	• • • • • • • • • • • • • • • • • • •	place
1/03/1	rapid quenched powders or	1/14708 {Fe-Ni based alloys (pure Fe or Ni
	ribbon flakes}	<u>H01F 1/14, H01F 1/16</u> or <u>H01F 1/20</u>)}
1/0572	• • • • • • • { with a protective layer }	$1/14716$ {in the form of sheets}
1/0573	• • • • • • • • • (obtained by reduction or by	1/14725 {with insulating coating}
	hydrogen decrepitation or	$1/14733$ {in the form of particles}
	embrittlement}	1/14741 {pressed, sintered or bonded
1/0574	(obtained by liquid dynamic	together}
1/0575	compaction}	1/1475 {the particles being insulated}
1/0575	• • • • • • { pressed, sintered or bonded together }	1/14758 {by macromolecular organic substances}
1/0576	• • • • • • • • {pressed, e.g. hot working}	1/14766 {Fe-Si based alloys}
1/0577	{sintered}	1/14775 {in the form of sheets}
1/0578	• • • • • • • • {bonded together}	1/14783 {with insulating coating}
1/0579	• • • • • • • { with exchange spin coupling	1/14791 {Fe-Si-Al based alloys, e.g. Sendust}
	between hard and soft	1/153 Amorphous metallic alloys, e.g. glassy
	nanophases, e.g. nanocomposite	metals {(making ferrous amorphous
1/050	spring magnets}	alloys <u>C22C 33/003</u>)}
1/058 1/059	and IVa elements, e.g. $Gd_2Fe_{14}C$ and Va elements, e.g. $Sm_2Fe_{17}N_2$	1/15308 {based on Fe/Ni (<u>H01F 1/15325</u> takes precedence)}
1/0593		1/15316 {based on Co (<u>H01F 1/15325</u> takes
1/0596		precedence)}
1,000	Th ₂ Zn ₁₇ structure or hexagonal	1/15325 {containing rare earths}
	Th ₂ Ni ₁₇ structure}	1/15333 {containing nanocrystallites, e.g.
1/06	in the form of particles, e.g. powder	obtained by annealing}
	(<u>H01F 1/047</u> takes precedence {; record	1/15341 {Preparation processes therefor}
4 /0 -4	carriers <u>G11B 5/70605</u> })	1/1535 {by powder metallurgy, e.g. spark
1/061	• • • • { with a protective layer}	erosion}
1/063	• • • • { with a non magnetic core}	1/15358 {Making agglomerates therefrom, e.g.
1/065	 {obtained by a reduction} {obtained by liquid dynamic	by pressing}
1/066	compaction}	1/15366 {using a binder} 1/15375 {using polymers}
1/068	• • • • • {having a L10 crystallographic	1/15383 {using polymers}
	structure, e.g. [Co,Fe][Pt,Pd]	(H01F 1/15366 takes precedence)
	(nano)particles}	1/15391 {Elongated structures, e.g. wires}
1/08	• • • • pressed, sintered, or bound together	1/16 in the form of sheets (<u>H01F 1/147</u> takes
1/083	• • • • • {in a bonding agent}	precedence)
1/086	{sintered}	1/18 with insulating coating

1/20	• • • • in the form of particles, e.g. powder (H01F 1/147 takes precedence)	3/00	Cores, Yokes, or armatures (magnetic materials H01F 1/00; permanent magnets H01F 7/02)
1/22	• • • • pressed, sintered, or bound together	2003/005	• {Magnetic cores for receiving several windings with
1/24	• • • • • • the particles being insulated		perpendicular axes, e.g. for antennae or inductive
1/26	by macromolecular organic		power transfer}
	substances	3/02	• made from sheets
1/28	dispersed or suspended in a bonding	3/04	 made from strips or ribbons
4 /0.0	agent	3/06	• made from wires
1/33	 mixtures of metallic and non-metallic particles; metallic particles having oxide skin non-metallic substances, e.g. ferrites 	3/08	 made from powder (powder coatings on sheets <u>H01F 3/02</u>; on strips or ribbons <u>H01F 3/04</u>; on wires <u>H01F 3/06</u>)
1/342	• • • • • • • • • • • • • • • • • • •	3/10	Composite arrangements of magnetic circuits
1/342	precedence)}	2003/103	• (Magnetic circuits with permanent magnets)
1/344	• • • • • {Ferrites, e.g. having a cubic spinel	2003/106	
	structure (X2+O)(Y23+O3), e.g.		different magnetic materials}
	magnetite Fe ₃ O ₄ }	3/12	Magnetic shunt paths
1/346	• • • • • • • $\{[(TO4) \ 3] \text{ with } T= Si, Al, Fe, Ga \}$	3/14	• Constrictions; Gaps, e.g. air-gaps (in magnetic
	(H01F 10/24 takes precedence; Faraday rotators G02F 1/09)}		shunt paths <u>H01F 3/12</u>)
1/348	• • • • • • • {Hexaferrites with decreased hardness	5/00	Coils (superconducting coils H01F 6/06; fixed
	or anisotropy, i.e. with increased	5/002	inductances of the signal type <u>H01F 17/00</u>) • {Printed circuit coils}
	permeability in the microwave	5/003	
	(GHz) range, e.g. having a hexagonal	2005/006	• {with conical spiral form}
1/26	crystallographic structure}	5/02	• wound on non-magnetic supports, e.g. formers
1/36	in the form of particles {(<u>H01F 1/346</u> , <u>H01F 1/348</u> and <u>H01F 1/38</u> take	2005/022	• • {wound on formers with several winding chambers separated by flanges, e.g. for high
	precedence)}		voltage applications}
1/37	in a bonding agent	2005/025	• • {wound on coaxial arrangement of two or more
1/375	Flexible bodies		formers}
1/38	amorphous, e.g. amorphous oxides	2005/027	• • {wound on formers for receiving several coils
1/40	• of magnetic semiconductor materials, e.g.		with perpendicular winding axes, e.g. for
1/401	CdCr ₂ S ₄ (devices using galvano-magnetic or similar effects <u>H10N 50/00</u>)	5/04	antennae or inductive power transfer} Arrangements of electric connections to coils, e.g. leads
1/401	· · · {diluted}	2005/043	• • {having multiple pin terminals, e.g. arranged in
	NOTE		two parallel lines at both sides of the coil}
	In group H01F 1/401, a diluted magnetic	2005/046	• • {Details of formers and pin terminals related to
	semiconductor (DMS) is classified in the last appropriate place	7.10.6	mounting on printed circuits}
	last appropriate place	5/06	. Insulation of windings
1/402	• • • { of II-VI type, e.g. Zn1-x Crx Se}	6/00	Superconducting magnets; Superconducting
1/404	• • • {of III-V type, e.g. In1-x Mnx As}		coils {(magnetic resonance assemblies using
1/405	• • • {of IV type, e.g. Ge1-xMnx}		superconducting coil systems G01R 33/3815)}
1/407	{Diluted non-magnetic ions in a magnetic	2006/001	• {Constructive details of inductive current limiters}
	cation-sublattice, e.g. perovskites, La1-x(Ba,Sr)xMnO3}	6/003	 {Methods and means for discharging superconductive storage (superconducting alloys
1/408	{half-metallic, i.e. having only one electronic		C22C; static memories with superconducting
	spin direction at the Fermi level, e.g.		elements G11C 11/44; superconducting
	CrO ₂ , Heusler alloys (<u>H01F 10/1936</u> takes		circuit breakers with contacts <u>H01H 33/004</u> ;
	precedence)}		superconducting switches for low power
1/42	• of organic or organo-metallic materials {, e.g. graphene}(<u>H01F 1/44</u> takes precedence)		<u>H03K 17/92</u> ; superconducting material <u>H10N 60/00</u> ; power cryotons <u>H10N 60/355</u>)}
1/44	• of magnetic liquids, e.g. ferrofluids (particles	6/005	• {Methods and means for increasing the stored
1/44	in a bonding agent <u>H01F 1/28</u> , <u>H01F 1/36</u> , {H01F 1/37})		energy in superconductive coils by increments (flux pumps)}
1/442	• { the magnetic component being a metal or alloy, e.g. Fe (H01F 1/447 takes precedence) }	6/006	• {Supplying energising or de-energising current; Flux pumps}
1/445	• {the magnetic component being a compound, e.g. Fe ₃ O ₄ (H01F 1/447 takes precedence)}	6/008	• • {Electric circuit arrangements for energising superconductive electromagnets}
1/447	• • {characterised by magnetoviscosity, e.g.	6/02	• Quenching; Protection arrangements during quenching {(protection circuits H02H 7/001)}
	magnetorheological, magnetothixotropic,	6/04	• Cooling
	magnetodilatant liquids (electrorheological fluids C10M 171/001)}	6/04	 Cooling Coils, e.g. winding, insulating, terminating or casing
	<u>C10M1171/001</u> /	0/00	arrangements therefor

6/065	• • {Feed-through bushings, terminals and joints (leading of conductors or axles through casings of transformers <u>H01F 27/04</u>)}	7/06	• Electromagnets; Actuators including electromagnets {(electric coils <u>H01F 5/00</u> ; devices for holding workpieces using electric force <u>B23Q 3/15</u> ;
7/00	Magnets (superconducting magnets H01F 6/00; for separation of solid materials or fluids B03C 1/00; for bench or like work-holders B23B 31/28, B23Q 3/00; work-holding devices B25B 11/00; lifting magnets B66C 1/00; {operating or controlling locks using permanent magnets E05B 47/0038; devices for holding a wing, e.g. door or window, by magnetic or electromagnetic attraction E05C 19/16; relieving load or bearings using magnetic means F16C 39/06}; for electric meters G01R; for relays H01H; {for electric discharge tubes H01J, e.g. H01J 3/24, H01J 23/10,		load-engaging elements for lifting articles electromagnetically <u>B66C 1/06</u> ; electromagnetic couplings <u>F16D 27/00</u> ; magnetic brakes <u>F16D 63/002</u> ; electromagnetically operated valves <u>F16K 11/24</u> , <u>F16K 31/00</u> ; analysing materials by magnetic means <u>G01N 27/72</u> , <u>G01N 27/80</u> ; electromagnets for winding mechanical clocks <u>G04C 1/02</u> ; electromagnetic relays <u>H01H 51/00</u> ; windings for salient poles of dynamo-electric machines <u>H02K 3/18</u> ; electromagnets for telegraphic communication <u>H04L</u> ; for arc lamps <u>H05B 31/28</u>)}
5 /02	H01J 29/68}; for dynamo-electric machines H02K)	2007/062	• • {Details of terminals or connectors for
7/02	Permanent magnets {[PM]}		electromagnets}
7/0205 7/021	 • {Magnetic circuits with PM in general} • • {Construction of PM (<u>H01F 7/0278</u> takes precedence; PM compositions <u>H01F 1/032</u>)} 	7/064	Circuit arrangements for actuating electromagnets (circuit arrangements for obtaining special operating characteristics
7/0215	{Flexible forms, sheets}		H01F 7/18; driving circuits for electromagnets
7/0221	• • • {Mounting means for PM, supporting, coating, encapsulating PM}		making use of a switching regulator H01H 47/325)}
7/0226	• • • {PM with variable field strength (H01F 7/0284	7/066	• • {Electromagnets with movable winding}
	takes precedence)}	2007/068	• • {using printed circuit coils}
7/0231	• • {Magnetic circuits with PM for power or force	7/08	• • with armatures
	generation}	7/081	• • • {Magnetic constructions}
7/0236	• • • {Magnetic suspension or levitation (for vehicles <u>B60L 13/04</u> ; magnetic bearings	2007/083	• {External yoke surrounding the coil bobbin, e.g. made of bent magnetic sheet}
T/02.42	<u>F16C 39/063</u>)}	2007/085	Yoke or polar piece between coil bobbin
7/0242 7/0247	• • {Magnetic drives, magnetic coupling devices}• • {Orientating, locating, transporting	2007/097	and armature having a gap, e.g. filled with nonmagnetic material }
7/0252	arrangements)	2007/086	Structural details of the armature
7/0252	• • • {PM holding devices (<u>H01F 7/021</u> , <u>H01F 7/0215</u> , <u>H01F 7/0226</u> take precedence)}	7/088	• • • {provided with means for absorbing shocks}
7/0257	• • • {Lifting, pick-up magnetic objects}	7/10	specially adapted for alternating current
7/0263	Closures, bags, bands, engagement devices with male and female parts}	7/11 7/12	reducing or eliminating the effects of eddy currents
7/0268	{Magnetic cylinders}	7/1205	having anti-chattering arrangements{having short-circuited conductors
7/0273	• • {Magnetic circuits with PM for magnetic field generation}	7/1203	(electromagnetic relays provided with short-circuited conducting sleeves
7/0278	• • • { for generating uniform fields, focusing, deflecting electrically charged particles	7/121	H01H 47/00)}Guiding or setting position of armatures, e.g.
	(for magnetic separation by Lorentz force <u>B03C 1/023</u> ; specially adapted for NMR	7/122	retaining armatures in their end position by permanent magnets {(H01F 7/1615,
7/0204	applications <u>G01R 33/383</u>)}		<u>H01F 7/1646</u> take precedence)}
7/0284	• • • • {using a trimmable or adjustable magnetic circuit, e.g. for a symmetric dipole or	7/123	by ancillary coil
	quadrupole magnetic field}	7/124	by mechanical latch, e.g. detent
7/0289	• • • {Transducers, loudspeakers, moving coil	7/126	Supporting or mounting
1/0269	arrangements}	7/127	Assembling
7/0294	. • {Detection, inspection, magnetic treatment}	7/128	Encapsulating, encasing or sealing
7/04	Means for releasing the attractive force	7/129	of armatures
7704	Means for releasing the attractive force	7/13	characterised by pulling-force characteristics
		7/14	• • • Pivoting armatures (<u>H01F 7/17</u> takes precedence)
		7/145	• • • • {Rotary electromagnets with variable gap (with fixed gap or torque motors H02K 26/00)}
		7/16	• • • Rectilinearly-movable armatures (<u>H01F 7/17</u> takes precedence)
		7/1607	• • • {Armatures entering the winding}
		7/1615	• • • • {Armatures or stationary parts of magnetic circuit having permanent magnet}
		7/1623	{Armatures having T-form}

2007/163 {with axial bearing}	7/202	• • • {Electromagnets for high magnetic field
7/1638 {Armatures not entering the winding}	77202	strength (for superconducting electromagnets
7/1646 {Armatures or stationary parts of magnetic		<u>H01F 6/00</u> ; for transformers or inductances
circuit having permanent magnet}	7/204	without a magnetic core <u>H01F 30/08</u>)}
7/1653 {Magnetic circuit having axially spaced	7/204 7/206	 {Circuits for energising or de-energising} {Electromagnets for lifting, handling or
pole-pieces} 2007/1661 {Electromagnets or actuators with anti-stick	7/200	transporting of magnetic pieces or material
disc}		(electromagnets for guidance of vehicles,
2007/1669 {Armatures actuated by current pulse, e.g.		workpieces <u>B65G 21/2009</u> ; for magnetic
bistable actuators}	2007/200	suspension or levitation <u>H02N 15/00</u>)}
2007/1676 {Means for avoiding or reducing eddy	2007/208	• • • {combined with permanent magnets}
currents in the magnetic circuit, e.g. radial slots}	10/00	Thin magnetic films, e.g. of one-domain structure
2007/1684 {Armature position measurement using		(magnetic record carriers <u>G11B 5/00</u> ; thin-film
coils}	10/002	magnetic stores <u>G11C</u>){Antiferromagnetic thin films, i.e. films exhibiting
2007/1692 {Electromagnets or actuators with two coils}	10/002	a Néel transition temperature (<u>H01F 10/3218</u> and
7/17 Pivoting and rectilinearly-movable armatures		<u>H01F 10/3268</u> take precedence)}
7/18 Circuit arrangements for obtaining desired	10/005	• {organic or organo-metallic films, e.g.
operating characteristics, e.g. for slow operation, for sequential energisation of		monomolecular films obtained by Langmuir-
windings, for high-speed energisation of	10/007	Blodgett technique, graphene } • {ultrathin or granular films (H01F 10/005 and
windings	10/007	H01F 10/3227 take precedence; applying ultrathin
7/1805 {Circuit arrangements for holding the		or granular layers to substrates <u>H01F 41/301</u>)}
operation of electromagnets or for holding the armature in attracted position with	10/06	characterised by the coupling or physical contact
reduced energising current (for holding relay	10/08	with connecting or interacting conductors characterised by magnetic layers ({H01F 10/32}
armature in attracted position with reduced	10/08	takes precedence }; applying thin magnetic films to
energising current <u>H01H 47/04</u> ; quick		substrates <u>H01F 41/14</u>)
energising of electro-dynamic machines <u>H02P 9/08</u> ; for quickly de-energising of	10/10	characterised by the composition
dynamo-electric generators <u>H02P 9/123</u>)}	10/12	being metals or alloys (intermetallic
7/1811 {demagnetising upon switching off,	10/123	compounds H01F 10/18)
removing residual magnetism}	10/123	• • • {having a L10 crystallographic structure, e.g. [Co,Fe][Pt,Pd] thin films}
7/1816 {making use of an energy accumulator (for relays <u>H01H 47/043</u>)}	10/126	• • • {containing rare earth metals (<u>H01F 10/133</u> takes precedence)}
2007/1822 {using a capacitor to produce a boost voltage}	10/13	• • • Amorphous metallic alloys, e.g. glassy metals {(H01F 10/3204 takes precedence)}
7/1827 {by changing number of serially-		
connected turns or windings (for relays H01H 47/06)}		NOTE
7/1833 {by changing number of parallel-		In this group, amorphous metallic alloys are classified in the last appropriate place
connected turns or windings (for relays		
<u>H01H 47/08</u>)}	10/131	{containing iron or nickel}
7/1838 {by switching-in or -out impedance (for relays H01H 47/10)}	10/132 10/133	 {containing cobalt} {containing rare earth metals}
7/1844 {Monitoring or fail-safe circuits (for relays	10/135	{containing rare earth metals}
<u>H01H 47/002</u>)}	10/136	{containing transition metals}
2007/185 {with armature position measurement}	10/137	{containing cobalt}
2007/1855 {using a stored table to deduce one	10/138	• • • • {containing nanocrystallites, e.g. obtained
variable from another} 2007/1861 {using derivative of measured variable}	10/14	by annealing}
2007/1866 {with regulation loop}	10/14	• • • containing iron or nickel ({H01F 10/126} , H01F 10/13, H01F 10/16 take precedence)
7/1872 {Bistable or bidirectional current devices		
(relays <u>H01H 47/226</u>)}		NOTE
7/1877 {controlling a plurality of loads}		In this group, alloys containing iron or nickel are classified in the last appropriate
7/1883 {by steepening leading and trailing edges of magnetisation pulse, e.g. printer drivers}		place
2007/1888 {using pulse width modulation}	10/142	{containing Si}
2007/1894 {minimizing impact energy on closure of magnetic circuit}	10/145	{containing Al, e.g. SENDUST}
7/20 • without armatures (cores H01F 3/00; coils	10/147	• • • • { with lattice under strain, e.g.
H01F 5/00 {; shaping metal by applying magnetic		expanded by interstitial nitrogen
forces <u>B21D 26/14</u> ; electromagnets specially		(<u>H01F 10/26</u> - <u>H01F 10/30</u> take precedence)}
adapted for NMR applications <u>G01R 33/381</u> })		

10/16	1.1. ((1701) 10 (100)	10/02/02	
	• • • containing cobalt ({ <u>H01F 10/126</u> },	10/3263	• • • {the exchange coupling being symmetric, e.g.
	<u>H01F 10/13</u> take precedence)		for dual spin valve, e.g. NiO/Co/Cu/Co/Cu/Co/
10/18	being compounds		NiO}
10/187	• • • • Amorphous compounds {(<u>H01F 10/3204</u>	10/3268	• • • {the exchange coupling being asymmetric,
	takes precedence)}		e.g. by use of additional pinning, by using
10/193	Magnetic semiconductor compounds		antiferromagnetic or ferromagnetic coupling
	{(in general H01F 1/40; multilayers, e.g.		interface, i.e. so-called spin-valve [SV]
	superlattices <u>H01F 10/3213</u>)}		structure, e.g. NiFe/Cu/NiFe/FeMn}
10/1933	• • • • {Perovskites}	10/3272	• • • {by use of anti-parallel coupled [APC]
10/1936	• • • • {Half-metallic, e.g. epitaxial CrO ₂ or		ferromagnetic layers, e.g. artificial
10,1700	NiMnSb films}		ferrimagnets [AFI], artificial [AAF] or
10/20	Ferrites		synthetic [SAF] anti-ferromagnets}
		10/3277	• • • • {by use of artificial ferrimagnets [AFI]
10/205	{Hexagonal ferrites}		only}
10/22	• • • • Orthoferrites $\{$, e.g. RFeO $_3$ (R= rare earth	10/3281	{only by use of asymmetry of the magnetic
	element) with orthorhombic structure}		film pair itself, i.e. so-called pseudospin
10/24	Garnets {(in general <u>H01F 1/346</u> ;		valve [PSV] structure, e.g. NiFe/Cu/Co}
	multilayers, e.g. superlattices	10/3286	• • • {Spin-exchange coupled multilayers having
	H01F 10/3209; applying magnetic	10/3200	at least one layer with perpendicular magnetic
	garnet films to substrates by sputtering		anisotropy}
	<u>H01F 41/186</u>)}	10/220	The state of the s
10/245	• • • • • {Modifications for enhancing	10/329	{Spin-exchange coupled multilayers wherein
	interaction with electromagnetic wave		the magnetisation of the free layer is switched
	energy}		by a spin-polarised current, e.g. spin torque
10/26	 characterised by the substrate or intermediate layers 		effect}
	$\{(\underline{\text{H01F }10/06} \text{ and } \underline{\text{H01F }10/32} \text{ take precedence})\}$	10/3295	• • • {Spin-exchange coupled multilayers wherein
10/265	• • {Magnetic multilayers non exchange-coupled		the magnetic pinned or free layers are
	(H01F 10/32 takes precedence)}		laminated without anti-parallel coupling within
10/28	• • characterised by the composition of the substrate		the pinned and free layers}
10/30	 characterised by the composition of the characterised by the composition of the 	13/00	Apparatus or processes for magnetising or
10/30	intermediate layers {, e.g. seed, buffer, template,	13/00	demagnetising ({devices for holding workpieces
	diffusion preventing, cap layers (H01F 10/06 and		using magnetic or electric force acting directly
10/22	H01F 10/32 take precedence)		on the workpieces <u>B23Q 3/15</u> }; for degaussing
10/32	• Spin-exchange-coupled multilayers, e.g.		ships B63G 9/06; for clocks or watches G04D 9/00;
	nanostructured superlattices {(applying spin-		{recording or erasing of information on magnetic
	exchange-coupled multilayers to substrates		record carriers G11B 5/00}; demagnetising
	<u>H01F 41/302</u>)}		arrangements for colour television <u>H04N 9/29</u>)
10/0001			• {Methods and devices for magnetising permanent
10/3204	• • {Exchange coupling of amorphous multilayers}	13/003	
10/3209	• • {Exchange coupling of garnet multilayers}		magnets (permanent magnets H01F 7/02)}
	• {Exchange coupling of garnet multilayers}• {Exchange coupling of magnetic semiconductor	13/003	magnets (permanent magnets <u>H01F 7/02</u>)} • {Methods and devices for demagnetising of
10/3209	 • {Exchange coupling of garnet multilayers} • {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices 		 magnets (permanent magnets H01F 7/02)} {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material
10/3209	 • {Exchange coupling of garnet multilayers} • {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in 		 magnets (permanent magnets <u>H01F 7/02</u>)} {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record
10/3209	 • {Exchange coupling of garnet multilayers} • {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} 		 magnets (permanent magnets H01F 7/02)} {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material
10/3209	 {Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an 	13/006	 magnets (permanent magnets <u>H01F 7/02</u>)} {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers <u>G11B 5/00</u>)}
10/3209 10/3213	 • {Exchange coupling of garnet multilayers} • {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} 		 magnets (permanent magnets H01F 7/02)} {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in
10/3209 10/3213	 {Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an 	13/006	magnets (permanent magnets <u>H01F 7/02</u>)} • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers <u>G11B 5/00</u>)} Fixed inductances of the signal type {(coils in general <u>H01F 5/00</u> ; inductors without a potential-
10/3209 10/3213	 Exchange coupling of garnet multilayers Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12) Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes 	13/006	magnets (permanent magnets <u>H01F 7/02</u>)} • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers <u>G11B 5/00</u>)} Fixed inductances of the signal type {(coils in general <u>H01F 5/00</u> ; inductors without a potential-jump or surface barrier specially adapted for
10/3209 10/3213 10/3218	 Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} {Exchange coupled hard/soft multilayers, e.g. 	13/006	magnets (permanent magnets H01F 7/02)} • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep
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10/3209 10/3213 10/3218	 Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} {Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm (nanocomposite spring magnets H01F 1/0579)} {Exchange coupling via one or more 	13/006 17/00	magnets (permanent magnets H01F 7/02)} • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor H01L 28/10)} • {Printed inductances (printed coils for dynamo-electric machines H02K 3/26; printed circuits
10/3209 10/3213 10/3218 10/3222 10/3227	 {Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} {Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm (nanocomposite spring magnets H01F 1/0579)} {Exchange coupling via one or more magnetisable ultrathin or granular films} 	13/006 17/00	magnets (permanent magnets H01F 7/02)} • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor H01L 28/10)} • {Printed inductances (printed coils for dynamo-electric machines H02K 3/26; printed circuits H05K)}
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10/3209 10/3213 10/3218 10/3222 10/3227 10/3231 10/3236	 Exchange coupling of garnet multilayers} Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm (nanocomposite spring magnets H01F 1/0579)} Exchange coupling via one or more magnetisable ultrathin or granular films} {via a non-magnetic spacer} {made of a noble metal, e.g.(Co/Pt) n multilayers having perpendicular anisotropy (H01F 10/3286 takes precedence)} 	13/006 17/00 17/0006 17/0013	magnets (permanent magnets H01F 7/02)} • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor H01L 28/10)} • {Printed inductances (printed coils for dynamo-electric machines H02K 3/26; printed circuits H05K)} • • {with stacked layers} • • {Details of via holes for interconnecting the layers}
10/3209 10/3213 10/3218 10/3222 10/3227 10/3231	 Exchange coupling of garnet multilayers} Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm (nanocomposite spring magnets H01F 1/0579)} Exchange coupling via one or more magnetisable ultrathin or granular films} {via a non-magnetic spacer} {made of a noble metal, e.g.(Co/Pt) n multilayers having perpendicular anisotropy (H01F 10/3286 takes precedence)} Exchange coupling of magnetic film pairs via a 	17/0006 17/0006 17/0013 2017/002 2017/0026	magnets (permanent magnets H01F 7/02)} • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor H01L 28/10)} • {Printed inductances (printed coils for dynamo-electric machines H02K 3/26; printed circuits H05K)} • • {with stacked layers} • • {Details of via holes for interconnecting the layers} • • {Multilayer LC-filter}
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10/3209 10/3213 10/3218 10/3222 10/3227 10/3231 10/3236 10/324	 Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} {Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm (nanocomposite spring magnets H01F 1/0579)} {Exchange coupling via one or more magnetisable ultrathin or granular films} { via a non-magnetic spacer} { made of a noble metal, e.g.(Co/Pt) n multilayers having perpendicular anisotropy (H01F 10/3286 takes precedence)} { Exchange coupling of magnetic film pairs via a very thin non-magnetic spacer, e.g. by exchange with conduction electrons of the spacer} { the spacer being superconductive} 	17/0006 17/0006 17/0013 2017/002 2017/0026	magnets (permanent magnets H01F 7/02)} • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor H01L 28/10)} • {Printed inductances (printed coils for dynamo-electric machines H02K 3/26; printed circuits H05K)} • • {With stacked layers} • • {Details of via holes for interconnecting the layers} • • {Multilayer LC-filter} • • {with the coil helically wound around a magnetic core}
10/3209 10/3213 10/3218 10/3222 10/3227 10/3231 10/3236 10/324 10/3245 10/325	 Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} {Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm (nanocomposite spring magnets H01F 1/0579)} {Exchange coupling via one or more magnetisable ultrathin or granular films} {via a non-magnetic spacer} {made of a noble metal, e.g.(Co/Pt) n multilayers having perpendicular anisotropy (H01F 10/3286 takes precedence)} {Exchange coupling of magnetic film pairs via a very thin non-magnetic spacer, e.g. by exchange with conduction electrons of the spacer} {the spacer being superconductive} {the spacer being noble metal} 	17/0006 17/0006 17/0013 2017/002 2017/0026 17/0033 2017/004	 magnets (permanent magnets H01F 7/02)} {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor H01L 28/10)} {Printed inductances (printed coils for dynamo-electric machines H02K 3/26; printed circuits H05K)} { with stacked layers} { Details of via holes for interconnecting the layers} { Multilayer LC-filter} { with the coil helically wound around a magnetic core} { with the coil helically wound around an axis without a core}
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10/3209 10/3213 10/3218 10/3222 10/3227 10/3231 10/3236 10/324 10/3245 10/325	 Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} {Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm (nanocomposite spring magnets H01F 1/0579)} {Exchange coupling via one or more magnetisable ultrathin or granular films} {via a non-magnetic spacer} {made of a noble metal, e.g.(Co/Pt) n multilayers having perpendicular anisotropy (H01F 10/3286 takes precedence)} {Exchange coupling of magnetic film pairs via a very thin non-magnetic spacer, e.g. by exchange with conduction electrons of the spacer} {the spacer being superconductive} {the spacer being noble metal} 	17/0006 17/0006 17/0013 2017/002 2017/0026 17/0033 2017/004 2017/0046 2017/0053	magnets (permanent magnets H01F 7/02)} • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor H01L 28/10)} • {Printed inductances (printed coils for dynamo-electric machines H02K 3/26; printed circuits H05K)} • {with stacked layers} • • {Details of via holes for interconnecting the layers} • • {Multilayer LC-filter} • • {with the coil helically wound around a magnetic core} • • {with a conductive path having a bridge} • • {with means to reduce eddy currents}
10/3209 10/3213 10/3218 10/3222 10/3227 10/3231 10/3236 10/324 10/3245 10/325	 Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} {Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm (nanocomposite spring magnets H01F 1/0579)} {Exchange coupling via one or more magnetisable ultrathin or granular films} {via a non-magnetic spacer} {made of a noble metal, e.g.(Co/Pt) n multilayers having perpendicular anisotropy (H01F 10/3286 takes precedence)} {Exchange coupling of magnetic film pairs via a very thin non-magnetic spacer, e.g. by exchange with conduction electrons of the spacer} {the spacer being superconductive} {the spacer being noble metal} {the spacer being semiconducting or insulating, 	17/0006 17/0006 17/0013 2017/002 2017/0026 17/0033 2017/004 2017/0046 2017/0053 2017/006	magnets (permanent magnets H01F 7/02) • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor H01L 28/10)} • {Printed inductances (printed coils for dynamo-electric machines H02K 3/26; printed circuits H05K)} • • {with stacked layers} • • {Details of via holes for interconnecting the layers} • • {Multilayer LC-filter} • • {with the coil helically wound around a magnetic core} • • {with the coil helically wound around an axis without a core} • • {with means to reduce eddy currents} • • {flexible printed inductors}
10/3209 10/3213 10/3218 10/3222 10/3227 10/3231 10/3236 10/324 10/324 10/325 10/3254	 Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor materials for use in semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} {Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm (nanocomposite spring magnets H01F 1/0579)} {Exchange coupling via one or more magnetisable ultrathin or granular films} {via a non-magnetic spacer} {made of a noble metal, e.g.(Co/Pt) n multilayers having perpendicular anisotropy (H01F 10/3286 takes precedence)} {Exchange coupling of magnetic film pairs via a very thin non-magnetic spacer, e.g. by exchange with conduction electrons of the spacer} {the spacer being superconductive} {the spacer being semiconducting or insulating, e.g. for spin tunnel junction [STJ]} 	17/0006 17/0006 17/0013 2017/0026 17/0033 2017/004 2017/0046 2017/0053 2017/006 2017/0066	magnets (permanent magnets H01F 7/02)} • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor H01L 28/10)} • {Printed inductances (printed coils for dynamo-electric machines H02K 3/26; printed circuits H05K)} • • {with stacked layers} • • {Details of via holes for interconnecting the layers} • • {Multilayer LC-filter} • • {with the coil helically wound around a magnetic core} • • {with the coil helically wound around an axis without a core} • • {with means to reduce eddy currents} • • {flexible printed inductors} • • {with a magnetic layer}
10/3209 10/3213 10/3218 10/3222 10/3227 10/3231 10/3236 10/324 10/324 10/325 10/3254	 Exchange coupling of garnet multilayers} {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe superlattices (semiconductor devices H01L 29/12)} {Exchange coupling of magnetic films via an antiferromagnetic interface (H01F 10/3268 takes precedence)} {Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm (nanocomposite spring magnets H01F 1/0579)} {Exchange coupling via one or more magnetisable ultrathin or granular films} {via a non-magnetic spacer} {made of a noble metal, e.g.(Co/Pt) n multilayers having perpendicular anisotropy (H01F 10/3286 takes precedence)} {Exchange coupling of magnetic film pairs via a very thin non-magnetic spacer, e.g. by exchange with conduction electrons of the spacer} {the spacer being superconductive} {the spacer being semiconducting or insulating, e.g. for spin tunnel junction [STJ]} {Spin-exchange-coupled multilayers} 	17/0006 17/0006 17/0013 2017/0026 17/0033 2017/004 2017/0046 2017/0053 2017/006 2017/0066	magnets (permanent magnets H01F 7/02) • {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers G11B 5/00)} Fixed inductances of the signal type {(coils in general H01F 5/00; inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor H01L 28/10)} • {Printed inductances (printed coils for dynamo-electric machines H02K 3/26; printed circuits H05K)} • • {with stacked layers} • • {Details of via holes for interconnecting the layers} • • {Multilayer LC-filter} • • {with the coil helically wound around a magnetic core} • • {with the coil helically wound around an axis without a core} • • {with means to reduce eddy currents} • • {flexible printed inductors}

2017/008	{Electric or magnetic shielding of printed	27/006	• {with special arrangement or spacing of turns of the
	inductances}		winding(s), e.g. to produce desired self-resonance}
2017/0086	• • {on semiconductor substrate (inductors for	27/008	• {with temperature compensation}
2017/0002	integrated circuits H01L 28/10)}	27/02	. Casings
2017/0093	• {Common mode choke coil}	27/022	{Encapsulation}
17/02	without magnetic core	27/025	• • {Constructional details relating to cooling}
17/03 17/04	• with ceramic former	27/027	{specially adapted for combination of signal type
17/04	. with magnetic core		inductors or transformers with electronic circuits, e.g. mounting on printed circuit boards}
17/041	 {Means for preventing rotation or displacement of the core} 	27/04	Leading of conductors or axles through casings,
17/043	• • {with two, usually identical or nearly identical		e.g. for tap-changing arrangements
	parts enclosing completely the coil (pot cores)}	27/06	 Mounting, supporting or suspending transformers,
17/045	• • { with core of cylindric geometry and coil wound		reactors or choke coils {not being of the signal
	along its longitudinal axis, i.e. rod or drum core}		type}
2017/046	• • • {helical coil made of flat wire, e.g. with smaller	2027/065	• • {Mounting on printed circuit boards}
	extension of wire cross section in the direction	27/08	• Cooling (heat-transfer elements <u>F28F</u>); Ventilating
2017/049	of the longitudinal axis}	27/095	(structural details of casings H01F 27/02)
2017/048	• { with encapsulating core, e.g. made of resin and magnetic powder}	27/085 27/10	. {Cooling by ambient air}. Liquid cooling
17/06	• with core substantially closed in itself, e.g. toroid	27/105	{Cooling by special liquid or by liquid of
17/062	{Toroidal core with turns of coil around it}	27/103	particular composition}
2017/065	{Core mounted around conductor to absorb	27/12	· · · Oil cooling
	noise, e.g. EMI filter}	27/125	• • • • • • • • • • • • • • • • • • •
2017/067	• • • {Core with two or more holes to lead through		incombustible liquid}
	conductor}	27/14	Expansion chambers; Oil conservators;
17/08	Loading coils for telecommunication circuits		Gas cushions; Arrangements for purifying,
19/00	Fixed transformers or mutual inductances of the		drying, or filling
15/00	signal type (H01F 36/00 takes precedence)	27/16	Water cooling
19/02	Audio-frequency transformers or mutual	27/18	• • by evaporating liquids
	inductances, i.e. not suitable for handling	27/20	• Cooling by special gases or non-ambient air
	frequencies considerably beyond the audio range	27/22	 Cooling by heat conduction through solid or powdered fillings
19/04	Transformers or mutual inductances suitable for	27/23	Corrosion protection
	handling frequencies considerably beyond the audio	27/24	Magnetic cores
19/06	range (resonant circuits <u>H03H</u>) • Broad-band transformers, e.g. suitable for	27/245	made from sheets, e.g. grain-oriented
19/00	handling frequencies well down into the audio		(H01F 27/26 takes precedence)
	range	27/2455	• • • {using bent laminations}
19/08	Transformers having magnetic bias, e.g. for	27/25	• • made from strips or ribbons (<u>H01F 27/26</u> takes
	handling pulses		precedence)
2019/085	• • {Transformer for galvanic isolation}	27/255	made from particles (H01F 27/26 takes
21/00	Variable inductances or transformers of the signal	27/26	precedence)
21/00	type (H01F 36/00 takes precedence)	27/26	Fastening parts of the core together; Fastening or mounting the core on casing or support (on coil
21/005	• {Inductances without magnetic core}		H01F 27/30)
21/02	continuously variable, e.g. variometers	27/263	• • • {Fastening parts of the core together}
21/04	by relative movement of turns or parts of	27/266	• • • {Fastening or mounting the core on casing or
	windings		support (on coil <u>H01F 27/30</u>)}
21/06	• • by movement of core or part of core relative to	27/28	 Coils; Windings; Conductive connections
	the windings as a whole	27/2804	• • {Printed windings}
21/065	{Measures for obtaining a desired relation	2027/2809	• • • {on stacked layers}
	between the position of the core and the inductance}	2027/2814	• • • { with only part of the coil or of the winding in
21/08	by varying the permeability of the core, e.g. by		the printed circuit board, e.g. the remaining coil
21/00	varying magnetic bias		or winding sections can be made of wires or sheets}
21/10	• by means of a movable shield	2027/2819	• • • {Planar transformers with printed windings,
21/12	discontinuously variable, e.g. tapped	2027/2017	e.g. surrounded by two cores and to be
2021/125	• • {Printed variable inductor with taps, e.g. for		mounted on printed circuit}
	VCO}	27/2823	• • {Wires (<u>H01F 27/2866</u> takes precedence)}
27/00	Details of transformers or inductances, in general	27/2828	• • • {Construction of conductive connections, of
27/002	• {Arrangements provided on the transformer		leads}
2,,002	facilitating its transport}	2027/2833	• • • {using coaxial cable as wire}
27/004	• {Arrangements for interchanging inductances,	2027/2838	• • · · {using transposed wires}
	transformers or coils thereof}		

2027/2842	• • • {Wire coils wound in conical zigzag to reduce voltage between winding turns}	27/346	• • {Preventing or reducing leakage fields (using magnetic shields <u>H01F 27/36</u> ; using auxiliary
27/2847	• • {Sheets; Strips (<u>H01F 27/2866</u> takes	2027/249	windings <u>H01F 27/38</u>)}
27/2852	precedence)}• (Construction of conductive connections, of	2027/348 27/36	 . {Preventing eddy currents} . Electric or magnetic shields or screens (movable)
21/2032	leads}	27/30	for varying inductance H01F 21/10)
2027/2857	{Coil formed from wound foil conductor}	27/361	• • • {made of combinations of electrically
2027/2861	{Coil formed by folding a blank}		conductive material and ferromagnetic
27/2866	• • {Combination of wires and sheets}	27/272	material}
27/2871	• • {Pancake coils}	27/363	• • • {made of electrically conductive material}
27/2876	• • {Cooling (cooling transformers and inductances	27/366 27/38	 {made of ferromagnetic material}. Auxiliary core members; Auxiliary coils or
27/288	in general <u>H01F 27/08</u>)} • • {Shielding}	21/36	windings
27/2885	• • {with shields or electrodes (shields or	27/385	{for reducing harmonics}
	electrodes for pancake coils H01F 27/2871;	27/40	 Structural association with built-in electric
	construction of electric or magnetic shields or		component, e.g. fuse
27/200	screens <u>H01F 27/36</u>)}	27/402	• • {Association of measuring or protective means}
27/289	• • • {with auxiliary windings (for pancake coils H01F 27/2871)}	2027/404	• • {Protective devices specially adapted for fluid filled transformers}
27/2895	• • {Windings disposed upon ring cores}	2027/406	{Temperature sensor or protection}
27/29	Terminals; Tapping arrangements { for signal	2027/408	{Association with diode or rectifier}
	inductances}	27/42	Circuits specially adapted for the purpose
27/292	• • • {Surface mounted devices}		of modifying, or compensating for, electric
2027/295	• • • • {with flexible terminals}		characteristics of transformers, reactors, or choke
2027/297	• {with pin-like terminal to be inserted in hole of		coils (circuits for controlling transformers, reactors or choke coils, for the purpose of obtaining a
27/30	printed path}Fastening or clamping coils, windings, or parts		desired output <u>H02P 13/00</u> ; impedance networks
21730	thereof together; Fastening or mounting coils or		<u>H03H</u>)
	windings on core, casing, or other support	27/422	• • {for instrument transformers}
27/303	{Clamping coils, windings or parts thereof	27/425	• • • {for voltage transformers}
27/206	together}	27/427	• • • {for current transformers}
27/306	 {Fastening or mounting coils or windings on core, casing or other support} 	29/00	Variable transformers or inductances not
27/32	Insulating of coils, windings, or parts thereof		covered by group H01F 21/00 {(tap change devices
	• • Histiating of Cons, windings, of parts dicicol		110111 0/0005)
27/321		29/02	H01H 9/0005)} with tannings on coil or winding; with provision for
	• • {using a fluid for insulating purposes only}• • {the insulation forming channels for circulation	29/02	• with tappings on coil or winding; with provision for
27/321 27/322	 {using a fluid for insulating purposes only} {the insulation forming channels for circulation of the fluid}	29/02 29/025	
27/321	 {using a fluid for insulating purposes only} {the insulation forming channels for circulation of the fluid} {Insulation between winding turns, between 	29/025	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings}
27/321 27/322 27/323	 • (using a fluid for insulating purposes only) • (the insulation forming channels for circulation of the fluid) • (Insulation between winding turns, between winding layers) 		 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without
27/321 27/322	 {using a fluid for insulating purposes only} {the insulation forming channels for circulation of the fluid} {Insulation between winding turns, between 	29/025 29/04	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current
27/321 27/322 27/323	 • (using a fluid for insulating purposes only) • (the insulation forming channels for circulation of the fluid) • (Insulation between winding turns, between winding layers) • (Insulation between coil and core, between different winding sections, around the coil; Other insulation structures) 	29/025	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along
27/321 27/322 27/323	 {using a fluid for insulating purposes only} {the insulation forming channels for circulation of the fluid} {Insulation between winding turns, between winding layers} {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} {Coil bobbins (formers for coils in general 	29/025 29/04	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current
27/321 27/322 27/323 27/324 27/325	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} 	29/025 29/04 29/06	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction
27/321 27/322 27/323 27/324	 {using a fluid for insulating purposes only} {the insulation forming channels for circulation of the fluid} {Insulation between winding turns, between winding layers} {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} {Coil bobbins (formers for coils in general H01F 5/02)} {specifically adapted for discharge lamp 	29/025 29/04 29/06 29/08	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators
27/321 27/322 27/323 27/324 27/325	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} • • {specifically adapted for discharge lamp ballasts} 	29/025 29/04 29/06	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high
27/321 27/322 27/323 27/324 27/325 27/326	 {using a fluid for insulating purposes only} {the insulation forming channels for circulation of the fluid} {Insulation between winding turns, between winding layers} {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} {Coil bobbins (formers for coils in general H01F 5/02)} {specifically adapted for discharge lamp 	29/025 29/04 29/06 29/08	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamo-
27/321 27/322 27/323 27/324 27/325 27/326	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} • • { specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • {Dry-type transformer with encapsulated foil 	29/025 29/04 29/06 29/08	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high
27/321 27/322 27/323 27/324 27/325 27/326 27/327	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} • • { specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on 	29/025 29/04 29/06 29/08	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamoelectric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof;
27/321 27/322 27/323 27/324 27/325 27/326 27/327	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with 	29/025 29/04 29/06 29/08 29/10	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamoelectric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield
27/321 27/322 27/323 27/324 27/325 27/326 27/327	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases} 	29/025 29/04 29/06 29/08 29/10	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamo-electric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield with variable magnetic bias ({amplitude}
27/321 27/322 27/323 27/324 27/325 27/326 27/327 2027/328	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases} • • {Insulation with semiconducting layer, e.g. to reduce corona effect} 	29/025 29/04 29/06 29/08 29/10	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamoelectric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield
27/321 27/322 27/323 27/324 27/325 27/326 27/327 2027/328 2027/329 27/33	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases} • • {Insulation with semiconducting layer, e.g. to reduce corona effect} • Arrangements for noise damping 	29/025 29/04 29/06 29/08 29/10	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamoelectric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield with variable magnetic bias ({amplitude modulation by means of variable impedance element H03C 1/08}; magnetic amplifiers H03F; {circuits for automatic telephonic communication
27/321 27/322 27/323 27/324 27/325 27/326 27/327 2027/328	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases} • • {Insulation with semiconducting layer, e.g. to reduce corona effect} • Arrangements for noise damping • Special means for preventing or reducing unwanted 	29/025 29/04 29/06 29/08 29/10 29/12 29/14	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamoelectric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield with variable magnetic bias ({amplitude modulation by means of variable impedance element H03C 1/08}; magnetic amplifiers H03F; {circuits for automatic telephonic communication H04M 3/00})
27/321 27/322 27/323 27/324 27/325 27/326 27/327 2027/328 2027/329 27/33	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases} • • {Insulation with semiconducting layer, e.g. to reduce corona effect} • Arrangements for noise damping • Special means for preventing or reducing unwanted electric or magnetic effects, e.g. no-load losses, 	29/025 29/04 29/06 29/08 29/10	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamo-electric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield with variable magnetic bias ({amplitude modulation by means of variable impedance element H03C 1/08}; magnetic amplifiers H03F; {circuits for automatic telephonic communication H04M 3/00}) {with control winding for generating magnetic
27/321 27/322 27/323 27/324 27/325 27/326 27/327 2027/328 2027/329 27/33	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • {Coil bobbins (formers for coils in general H01F 5/02)} • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases} • • {Insulation with semiconducting layer, e.g. to reduce corona effect} • Arrangements for noise damping • Special means for preventing or reducing unwanted 	29/025 29/04 29/06 29/08 29/10 29/12 29/14	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamo-electric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield with variable magnetic bias ({amplitude modulation by means of variable impedance element H03C 1/08}; magnetic amplifiers H03F; {circuits for automatic telephonic communication H04M 3/00}) {with control winding for generating magnetic bias}
27/321 27/322 27/323 27/324 27/325 27/326 27/327 2027/328 2027/329 27/33	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • • {Coil bobbins (formers for coils in general H01F 5/02)} • • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases} • • {Insulation with semiconducting layer, e.g. to reduce corona effect} • Arrangements for noise damping • Special means for preventing or reducing unwanted electric or magnetic effects, e.g. no-load losses, reactive currents, harmonics, oscillations, leakage fields • {Preventing or reducing no-load losses or reactive 	29/025 29/04 29/06 29/08 29/10 29/12 29/14 2029/143 29/146	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamoelectric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield with variable magnetic bias ({amplitude modulation by means of variable impedance element H03C 1/08}; magnetic amplifiers H03F; {circuits for automatic telephonic communication H04M 3/00}) {with control winding for generating magnetic bias} {Constructional details}
27/321 27/322 27/323 27/324 27/325 27/326 27/327 2027/328 2027/329 27/33 27/34	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • • {Coil bobbins (formers for coils in general H01F 5/02)} • • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases} • • {Insulation with semiconducting layer, e.g. to reduce corona effect} • Arrangements for noise damping • Special means for preventing or reducing unwanted electric or magnetic effects, e.g. no-load losses, reactive currents, harmonics, oscillations, leakage fields • {Preventing or reducing no-load losses or reactive currents} 	29/025 29/04 29/06 29/08 29/10 29/12 29/14	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamoelectric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield with variable magnetic bias ({amplitude modulation by means of variable impedance element H03C 1/08}; magnetic amplifiers H03F; {circuits for automatic telephonic communication H04M 3/00}) {with control winding for generating magnetic bias} {Constructional details} Fixed transformers not covered by group
27/321 27/322 27/323 27/324 27/325 27/326 27/327 2027/328 2027/329 27/33 27/34	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • • {Coil bobbins (formers for coils in general H01F 5/02)} • • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases} • • {Insulation with semiconducting layer, e.g. to reduce corona effect} • Arrangements for noise damping • Special means for preventing or reducing unwanted electric or magnetic effects, e.g. no-load losses, reactive currents, harmonics, oscillations, leakage fields • {Preventing or reducing no-load losses or reactive currents} • {Preventing or reducing surge voltages; 	29/025 29/04 29/06 29/08 29/10 29/12 29/14 2029/143 29/146 30/00	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamo-electric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield with variable magnetic bias ({amplitude modulation by means of variable impedance element H03C 1/08}; magnetic amplifiers H03F; {circuits for automatic telephonic communication H04M 3/00}) {with control winding for generating magnetic bias} {Constructional details} Fixed transformers not covered by group H01F 19/00
27/321 27/322 27/323 27/324 27/325 27/326 27/327 2027/328 2027/329 27/33 27/34	 • • {using a fluid for insulating purposes only} • • {the insulation forming channels for circulation of the fluid} • • {Insulation between winding turns, between winding layers} • • {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures} • • • {Coil bobbins (formers for coils in general H01F 5/02)} • • • {specifically adapted for discharge lamp ballasts} • • {Encapsulating or impregnating (encapsulating coil and core H01F 27/022)} • • • {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases} • • {Insulation with semiconducting layer, e.g. to reduce corona effect} • Arrangements for noise damping • Special means for preventing or reducing unwanted electric or magnetic effects, e.g. no-load losses, reactive currents, harmonics, oscillations, leakage fields • {Preventing or reducing no-load losses or reactive currents} 	29/025 29/04 29/06 29/08 29/10 29/12 29/14 2029/143 29/146	 with tappings on coil or winding; with provision for rearrangement or interconnection of windings {Constructional details of transformers or reactors with tapping on coil or windings} having provision for tap-changing without interrupting the load current with current collector gliding or rolling on or along winding with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators having movable part of magnetic circuit {(high leakage transformers H01F 38/08; dynamoelectric machines with movable part of magnetic circuit H02K 23/44, H02K 23/48)} having movable coil, winding, or part thereof; having movable shield with variable magnetic bias ({amplitude modulation by means of variable impedance element H03C 1/08}; magnetic amplifiers H03F; {circuits for automatic telephonic communication H04M 3/00}) {with control winding for generating magnetic bias} {Constructional details} Fixed transformers not covered by group

30/04	 having two or more secondary windings, each supplying a separate load, e.g. for radio set power supplies characterised by the structure 	41/00	Apparatus or processes specially adapted for manufacturing or assembling magnets, inductances or transformers; Apparatus or processes specially adapted for manufacturing
30/08	without magnetic core		materials characterised by their magnetic
30/10	• • Single-phase transformers (<u>H01F 30/16</u> takes precedence)		properties NOTE
30/12	Two-phase, three-phase or polyphase transformers		Group H01F 41/30 takes precedence over groups
30/14	for changing the number of phases		$\underline{\text{H01F 41/16}}$ - $\underline{\text{H01F 41/24}}$ {, and over group
30/16	Toroidal transformers		<u>H01F 41/32</u> .
			This Note corresponds to IPC Note (1) relating to
36/00	Transformers with superconductive windings or with windings operating at cryogenic temperature	41/005	<u>H01F 41/16</u> - <u>H01F 41/24</u> , <u>H01F 41/32</u> .}
	(superconducting magnets or superconducting coils H01F 6/00)	41/005	• {Impregnating or encapsulating (insulating of windings <u>H01F 41/12</u>)}
37/00	Fixed inductances not covered by group	41/02	• for manufacturing cores, coils, or magnets (<u>H01F 41/14</u> takes precedence; for dynamo-electric
2= /00=	<u>H01F 17/00</u>		machines <u>H02K 15/00</u>)
37/005 38/00	• {without magnetic core} Adaptations of transformers or inductances for	41/0206	• • {Manufacturing of magnetic cores by mechanical means (magnetic cores per se H01F 27/24)}
30/00	specific applications or functions	41/0213	{Manufacturing of magnetic circuits made
2038/003	• {High frequency transformer for microwave oven}		from strip(s) or ribbon(s) (magnetic cores made
2038/005	• {matrix transformer consisting of several		by winding a ribbon $\underline{H01F27/25}$)
2038/000	interconnected individual transformers working as a whole}	41/022	• • • {by winding the strips or ribbons around a coil}
38/02	• for non-linear operation	41/0226	• • • {from amorphous ribbons}
38/023	• {of inductances}	41/0233	{Manufacturing of magnetic circuits made
2038/026	{or inductances} {non-linear inductive arrangements for		from sheets (magnetic cores made from sheets
	converters, e.g. with additional windings}		<u>H01F 27/245</u> ; soft magnetic alloys in the form of sheets <u>H01F 1/16</u>)}
38/04	• for frequency changing	41/024	{Manufacturing of magnetic circuits made
38/06	• for changing the wave shape		from deformed sheets (magnetic cores made
38/08	High-leakage transformers or inductances		from deformed sheets <u>H01F 27/2455</u>)}
38/085	• • {Welding transformers}	41/0246	• • • {Manufacturing of magnetic circuits by
38/10	Ballasts, e.g. for discharge lamps		moulding or by pressing powder (magnetic
38/12	. Ignition, e.g. for IC engines		cores made by moulding or by pressing
2038/122	{with rod-shaped core}		powder <u>H01F 27/255</u> ; soft magnetic particles <u>H01F 1/20</u> , <u>H01F 1/36</u>)}
2038/125	• • {with oil insulation}	41/0253	• {for manufacturing permanent magnets}
2038/127	{with magnetic circuit including permanent	41/0233	{for manufacturing permanent magnets} {protecting methods against environmental}
20/14	magnet}	41/020	influences, e.g. oxygen, by surface treatment
38/14	 Inductive couplings {(for wireless supply or distribution of electric power using inductive coupling H02J 50/10)} 		(magnetic particles with skin <u>H01F 1/061</u> , <u>H01F 1/09</u> , <u>H01F 1/24</u> , <u>H01F 1/33</u> and
2038/143	• • {for signals}		<u>G11B 5/706</u>)}
2038/146	• • {in combination with capacitive coupling}	41/0266	• • • {Moulding; Pressing (<u>H01F 41/0273</u> takes
38/16	Cascade transformers, e.g. for use with extra high tension		precedence; hard magnetic particles <u>H01F 1/06</u> , <u>H01F 1/11</u>)}
38/18	Rotary transformers	41/0273	• • • {Imparting anisotropy (methods and
38/20	Instruments transformers		devices for magnetising permanent magnets
38/22	for single phase ac		<u>H01F 13/003</u>)}
38/24	· · · Voltage transformers	41/028	• • • • {Radial anisotropy (for rotor or stator bodies
38/26	Constructions	41/0207	<u>H02K 15/02</u>)}
38/28	Current transformers	41/0286	{Trimming}
38/30	Constructions	41/0293	{diffusion of rare earth elements, e.g. Tb, Dy or
2038/305	{with toroidal magnetic core}	41/04	Ho, into permanent magnets}
38/32	Circuit arrangements	41/04	 for manufacturing coils {(coils for transformer or inductances H01F 27/28)}
38/34	Combined voltage and current transformers	41/041	• • {Printed circuit coils (apparatus or processes
38/36	Constructions	41/041	for manufacturing printed circuits in general
38/38	• • for polyphase ac		H05K 3/00)}
38/40	. for dc	41/042	• • • {by thin film techniques}
38/42	Flyback transformers	41/043	{by thick film techniques}
2038/423	• • {with adjusting potentiometers}	41/045	{Trimming}
2038/426	 \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	1 1/04J	• • • • [1111111111115]
2000/120	(Bap danistormer core)		

41/046	{structurally combined with ferromagnetic	41/186	• • • {for applying a magnetic garnet film (magnetic
41/047	material }		garnet materials <u>H01F 1/346</u> ; magnetic garnet films <u>H01F 10/24</u>)}
41/047	 {structurally combined with superconductive material} 	41/20	• by evaporation
41/048	{Superconductive coils}	41/205	• • {by laser ablation, e.g. pulsed laser deposition
41/06	Coil winding	11/203	[PLD]}
41/061	Winding flat conductive wires or sheets	41/22	Heat treatment; Thermal decomposition;
41/063	with insulation		Chemical vapour deposition
41/064	Winding non-flat conductive wires, e.g. rods,	41/24	• • from liquids
. 1, 00 .	cables or cords	41/26	• • • using electric currents {, e.g. electroplating}
41/066	• • • • with insulation	41/28	by liquid phase epitaxy
41/068	in the form of strip material	41/30	for applying nanostructures, e.g. by molecular
41/069	Winding two or more wires, e.g. bifilar		beam epitaxy [MBE]
	winding	41/301	• • • {for applying ultrathin or granular layers
41/07	Twisting		(ultrathin or granular layers <u>H01F 10/007</u>)}
41/071	Winding coils of special form (winding	41/302	• • • {for applying spin-exchange-coupled
	conductors onto closed formers or cores		multilayers, e.g. nanostructured superlattices
	$\underline{\text{H01F 41/08}}$)		(spin-exchange-coupled multilayers
2041/0711	• • • • {Winding saddle or deflection coils}	41/303	H01F 10/32)}
41/073	Winding onto elongate formers	41/303	• • • { with exchange coupling adjustment of magnetic film pairs, e.g. interface
41/074	Winding flat coils		modifications by reduction, oxidation}
41/076	Forming taps or terminals while winding,	41/304	• • • • • {using temporary decoupling, e.g.
	e.g. by wrapping or soldering the wire onto	.1,00.	involving blocking, Néel or Curie
	pins, or by directly forming terminals from the wire		temperature transitions by heat treatment
41/077	Deforming the cross section or shape of the		in presence/absence of a magnetic field}
41/0//	winding material while winding	41/305	• • • {applying the spacer or adjusting its
41/079	Measuring electrical characteristics while		interface, e.g. in order to enable particular
	winding	44.00	effect different from exchange coupling}
41/08	Winding conductors onto closed formers	41/306	{conductive spacer}
	or cores, e.g. threading conductors through	41/307	• • • • {insulating or semiconductive spacer}
	toroidal cores	41/308	{lift-off processes, e.g. ion milling, for
41/082	Devices for guiding or positioning the	41/309	trimming or patterning } {electroless or electrodeposition processes
44.004	winding material on the former	41/309	from plating solution}
41/084	for forming pancake coils	41/32	 for applying conductive, insulating or magnetic
41/086	in a special configuration on the former,	11/32	material on a magnetic film {, specially adapted for
41/000	e.g. orthocyclic coils or open mesh coils		a thin magnetic film}
41/088 41/09	 using revolving flyers Winding machines having two or more work	41/325	• • {applying a noble metal capping on a spin-
41/09	holders or formers		exchange-coupled multilayer, e.g. spin filter
41/092	Turrets; Turntables		deposition}
41/094	Tensioning or braking devices	41/34	• • in patterns, e.g. by lithography
41/096	Dispensing or feeding devices		
41/098	Mandrels; Formers		
41/10	Connecting leads to windings (making electric		
	connections in general H01R 43/00)		
41/12	• • • Insulating of windings ({impregnating or		
	encapsulating of transformers <u>H01F 41/005</u> };		
	of conductors in general <u>H01B 13/06</u>)		
41/122	{Insulating between turns or between		
41/105	winding layers}		
41/125	• • • • Other insulating structures; Insulating between coil and core, between different		
	winding sections, around the coil}		
41/127	• • • {Encapsulating or impregnating		
F1/12/	(encapsulating coil and core H01F 41/005)}		
41/14	• for applying magnetic films to substrates		
41/16	the magnetic material being applied in the		
	form of particles, e.g. by serigraphy {, to form		
	thick magnetic films or precursors therefor}		
	$(\underline{\text{H01F 41/18}} \{-\underline{\text{H01F 41/24}}\} \text{ take precedence})$		
41/18	by cathode sputtering		
41/183	• • • {Sputtering targets therefor}		